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There is still another type of wafer blade with the same shape as Figure 1B, which is made of ceramic or quartz without vacuum passageway.

In the Claims

~~Claim~~ 3 has been canceled without prejudice.

Claim 1 has been amended as follows:

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1. (Amended) A wafer blade for picking up wafers on a top surface of the blade and for detecting any undesirable contact with wafers on a bottom surface of the blade comprising:

a blade body of generally elongated shape having a top surface and a bottom surface parallel to each other; and

a strain sensor mounted on and at least partially covers said bottom surface of the blade body, said strain sensor is sensitive to at least 1 μ m strain.

Claim 11 has been amended as follows:

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11. (Amended) A wafer blade for picking up wafers according to claim 8, wherein said blade body is fabricated of a metal or a ceramic.

Claim 14 has been amended as follows:

14. (Amended) A wafer pick-up system comprising:

A_g a wafer blade having a blade body of generally elongated shape; said blade body having a top surface and a bottom surface;

a strain sensor mounted on said bottom surface of the blade body, said strain sensor is sensitive to at least 1 μ m strain; and

an alarm device for receiving a signal from said strain sensor when a strain is detected and for sending an alarm signal to alert an operator.

REMARKS

Thorough examination and careful review of the application by the Examiner is noted and appreciated.

Claims 1-20 are pending in the application. Claims 1-20 stand rejected.

Independent Claim 1 has been amended to more narrowly define the invention contained therein. Independent Claim 1 now recites the additional limitation of: